

VIA[®] CONNECTOR

5G RF board-to-board solution

- » Smart board-to-board and board-to-filter solution
- » Excellent blind mate - fast and safe assembling
- » Reliable, advanced, and secure connection
- » Low mating profile with minimum board-to-board distance of 12 mm

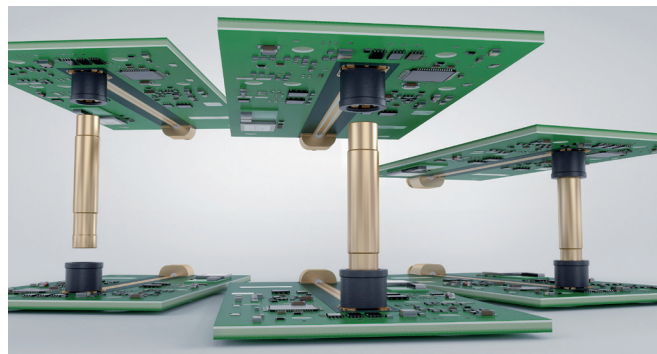


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5G RF board-to-board solution

VIA[®] (Variable Interface Adapter) is designed for board-to-board and board-to-filter RF interconnections in today's and future 5G applications.

The enhancement of the mechanical design is outstanding: limited detent and smooth bore interfaces are integrated into the adapter – one side of the adapter has mechanical retention to provide limited detent and the other side is smooth bore. The same PCB type could be used on both sides of the connection. For our customers, this results in a lower number of different parts on the BOM and lower costs.

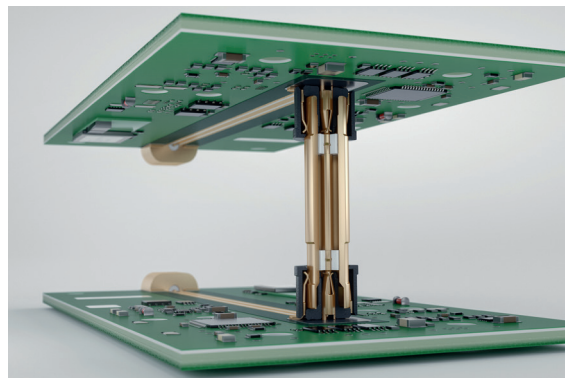


Product Features

- » Combines all the advantages of board-to-board connections (SMP, Longwipe-SMP, P-SMP)
- » Reliable, advanced, and secure connection
- » Excellent blind mate – fast and safe assembling
- » Same PCB type on both PCB sides simplifies assembly and the BOM
- » Limited detent or smooth bore side defined by the adapter
- » Low mating profile with minimum board-to-board distance of 12mm
- » Available as SMD & Thru-Hole component
- » Options for enhanced funnel:
 - » PCB-connector with pre-assembled enhanced funnel
 - » Enhanced funnel which could be assembled by the customer optionally

Characteristics

- » Axial tolerance: ± 1 mm
- » Radial tolerance: 4° : board-to-board distance < 16.5 mm
 ± 0.6 mm: board-to-board distance > 16.5 mm
- » Frequency range: DC to 6 GHz
- » Power: 100 W @ 2.2 GHz @ 20 °C
- » Return loss: ≥ 36 dB (typ.) @ DC to 2.5 GHz depending on axial misalignment



APPLICATIONS

- » Radios and filters in Small Cells
- » Radios and filters in Macro Cells
- » Distributed Antenna Systems (DAS)
- » In-building antennas
- » Massive MIMO antennas
- » Antenna interconnection solutions



Product portfolio

	Picture	Part number (P/N)	Description	Packaging	Plating
Board-to-board		5400.VIA.2010.003	PCB mount jack	Tape and reel packaging	3 = NiP + Au
		5401.VIA.2010.003	PCB mount jack	Tape and reel packaging	3 = NiP + Au
		5402.VIA.7910.003	VIA(m) – VIA(m) Adapter, Length 8.5 mm	Bulk packaging	3 = NiP + Au or 5 = White bronze (optional)
		5403.VIA.7910.003	VIA(m) – VIA(m) Adapter, Length 40 mm	Bulk packaging	3 = NiP + Au or 5 = White bronze (optional)
Board-to-panel		5400.VIA.2010.003	PCB mount jack	Tape and reel packaging	3 = NiP + Au
		5416.VIAP.8910.005	VIA(m) – VIA(m) Adapter	Bulk packaging	5 = White bronze
		5415.VIAP.2010.195	Bulkhead jack	Bulk packaging	5 = White bronze



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